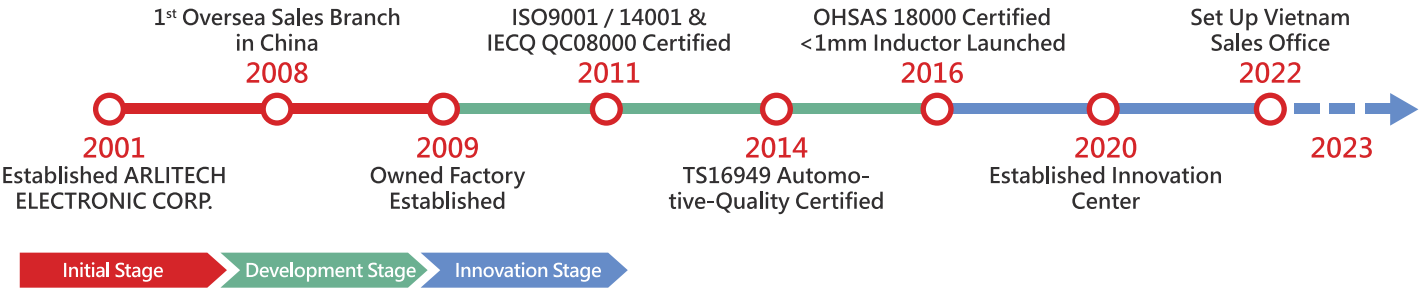
About Us

Arlitech Electronic Corp. (Arlitech) is one of the major inductors suppliers in Great China area, and LCD panel industry is our main market.

As the power consumption increases, more attention is paid to the wireless transmission quality and more strigent in mainly requirement of electrical characteristics. As a result, the application in using inductors is getting wider. Our inductors are used in various indstries such as Panel, Netcom, smart meters and consumer electronics industries, and also aim at penetrating into segments of industry and automotive electronics, medical and white goods.



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INDEX

Brand Line Card

	Arlitech	Artery	PANJIT	NIDEC	JDX	ROHM
DRAM						★
FLASH						
EEPROM						★
M0 MCU		★				
M4 MCU		★				★
LED Driver						★
Power Management						★
USB Type-C						★
PFC IC			★			★
PWM IC			★			★
SIC MOS/DIODE			★			★
MOSFET			★			★
IGBT			★			
Resistor						★
Capacitor					★	★
TVS/ESD/Zener			★			★
DC FAN				★		
Motor				★		
Power Inductor	★					
Aluminum Extruded Heat Sink	★					
Thermal Module	★					
Thermal Solution for Intel Server	★					
Thermal Solution for AMD Server	★					
High Thermal Conductivity Die-Casting	★					
Graphene Spray	★					
Thermal Conductivity	★					
Solimatrix FUSE						
Automotive Series FUSE						
GDT						
SPD						
OCP/OVP						

Brand Line Card

	ISSI	Puya	AEM	Bencent	POLYTRONICS	BYT
DRAM	★					
FLASH	★	★				
EEPROM		★				
M0 MCU						
M4 MCU						
LED Driver						
Power Management						
USB Type-C						
PFC IC						
PWM IC						
SIC MOS/DIODE						
MOSFET						
IGBT						
Resistor						
Capacitor						
TVS/ESD/Zener				★	★	
DC FAN						
Motor						
Power Inductor						
Aluminum Extruded Heat Sink						
Thermal Module						
Thermal Solution for Intel Server						
Thermal Solution for AMD Server						
High Thermal Conductivity Die-Casting						
Graphene Spray						
Thermal Conductivity						
Solimatrix FUSE						
Automotive Series FUSE			★			★
GDT			★	★	★	
SPD				★		
OCP/OVP					★	

Overall Serivice Introduction

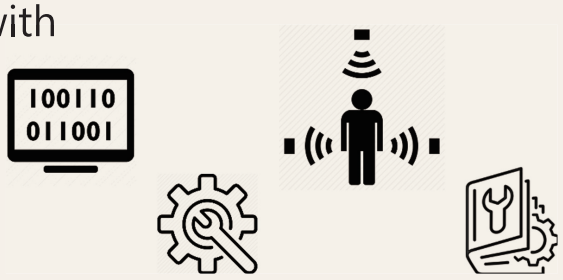
Active & Passive Component

Arlitech's supply chain combines by Power Inductors, Metal-Oxide Semiconductor Field-Effect Transistor (MOSFET), super capacitors, OVP, OCP, DRAM, amplifier, MCU, flash, and thermal fans. For Power Inductor, we provide shielded winding power chokes, dip inductors, and other types.

ARLITECH ARTERY PANJIT SEMICONDUCTOR JDX Nidec

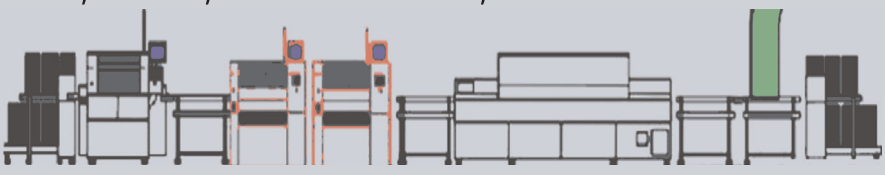
Design Solution

Except electronic parts sales, Arlitech also brings in IOT design service helps clients with product developement, solution survey, material study till final production.



SMT Assembly

We can offer more than 6 SMT and assembly line capacity. Our SMT strategic partner factory loactes at Hanoi with capability of more than two-point-sixty-seven trillion chips per month. Customer industries cover by IOT, Digital Meter, PCBA, Main Harness, and Consumer Electronics, etc.



Agent Line Introduction

Artery Technology Corporation

15

Artery Technology (Chongqing) Co., Ltd. was established in 2016. It is a chip (MCU) design company dedicated to promoting the innovation trend of 32-bit microcontrollers in the global market. Technical support branch. Arteli focuses on the R&D and innovation of ARM®Cortex®-M4/M0+ 32-bit microcontrollers. The full range of products adopts 55nm advanced technology and ARM® Cortex®-M4 high-performance or M0+ low-power cores, constantly building higher Performance and competitive MCU products.

PANJIT International Inc.

17

PANJIT is a semiconductor manufacturer founded in 1986. We own IDM design capability and continuously invest packaging miniaturization, wafer capacity expansion, R&D in advanced high power discrete solution and power IC design capability. We are also dedicated to product device development of EV, home appliance, solar power, UPS, energy storage systems and automotive to create much greener and smarter lives for the world.

NIDEC Corporation

19

Nidec Group specializes and handles motor application products based on "everything that spins and moves," centering around a motor business that comprises an expansive product line from small precision to supersized motors.

JDX Technology Co.,Ltd.

22

JDX's professional marketing team combines semiconductor IC components and related electronic circuits. Active IC and passive components (capacitors, inductors, transformers...etc.) system solution sales, our goal is to provide customers with higher-value competitive solutions and products and to improve the quality and price of customers' better products Advantages, rapid delivery, ... and other services to create win-win or multi-win business opportunities.

The main production items include:

- Low-voltage power capacitors and low-voltage power reactors are the main component.
- A full range of aluminum electrolytic capacitors, the exporter of alumi num electrolytic capacitor design and process technology.

Agent Line Introduction

ROHM Co., Ltd

27

ROHM was established in Kyoto in 1958 as initially a manufacturer of small electronic components. In 1967 production was expanded to include transistors and diodes, and ICs and other semiconductor products were added into product line from 1969.

INTEGRATED Silicon Solution, INC.

28

ISSI is a technology leader that designs, develops, and markets high performance integrated circuits for the following key markets: automotive, communications, digital consumer, and industrial and medical. Our primary products are high speed and low power SRAM and low and medium density DRAM. The Company also designs and markets NOR flash products and high performance analog and mixed signal integrated circuits.

Puya Semiconductor Co., Ltd.

30

Puya Semiconductor (Shanghai) Co., Ltd. is a supplier of low power SPI NOR Flash memory ICs and high reliability EEPORM memory ICs. As a technology innovator, Puya leverages state-of-the-art design and process advantage with leading foundries to develop 28-55nm high performance and high reliability SPI flash memories for conventional consumer, industrial markets and automotive as well as emerging applications. We also produces very competitive die size and performance advantage the flash memories are also ideal for MCP of SOC and MCU.

AEM Components, INC.

31

AEM is committed to the research, development, manufacturing and distribution of circuit protection components. We are well-known in the industry for providing the most extensive and comprehensive surface mount fuse lines and ESD protection. Our products, include SolidMatrix® SMD fuse, GcDiode® ultra low capacitance ESD Suppressors, AirMatrix® SMD fuse, multilayer varistors, ferrite beads, and inductors.

Agent Line Introduction

Bencent Electronics Co., Ltd.

32

Shenzhen Bencent Electronics Co., Ltd was established in 1999. With 17 years focus on development, production and distribution of GDT, TSS, TVS, ESD and compound component. The application portfolios include communication, security, consuming electronics, industrial, surge protection device (SPD), medical electronics, automotive electronics and alternative energy.

POLYTRONICS Technology Corp.

35

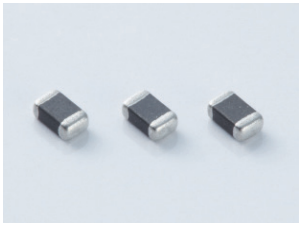
Polytronics Technology Corporation (PTTC) designs, develops and manufactures circuit protection devices that ensure the safety and reliability of today's high density electronics systems. Product families include surface-mount devices (SMDs), radial-leaded devices (RLDs), axial-leaded devices (ALDs) and many other custom-designed products. Industry applications included Computers, Peripherals, General Electronics, Batteries, Telecommunications systems, etc.

Zhuhai Boya Technology Co., Ltd.

36

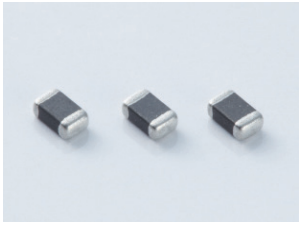
ZHUHAI BOYA TECHNOLOGY CO., LTD settled in Zhuhai New-high Technology Industrial Zone in December 2014 which has a senior team concentrated on advanced flash memory research and development. BOYA insist to achieve the dream of China chips. Our team familiar with the industry chain and master the core technology of the memory chip design. In the memory research, we are in the leading domestic level.

High Current Power Inductors



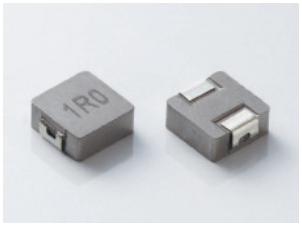
AMPI_CN Series

201610



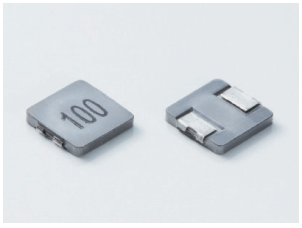
AMPI_EC Series

201610/252010/252012



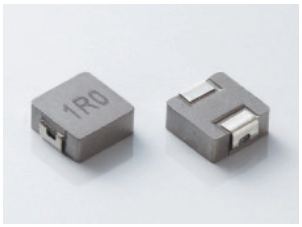
AMPI ED Series

0420/0530/0612/0618/0624/
0630/1040



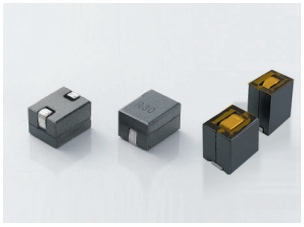
AMPI ECH Series

0410/0610



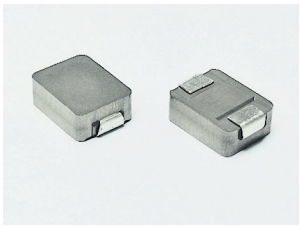
AMPI_EL_A Series

0420/0603/1265



AHCI Series

106580/100807/100808/
117575/090608/100609L/
100612L



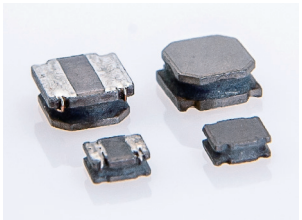
AMPI Vcore Series

100740/095640/0630/0640/
0530/0420

SMD Power Inductors

AQH_MK Series

201610/201612/252010/
252012

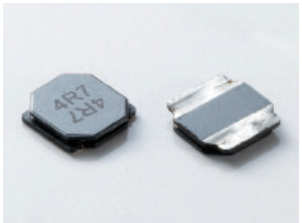


AHNR Series

201610/252010/252012/
3012/3015/4020

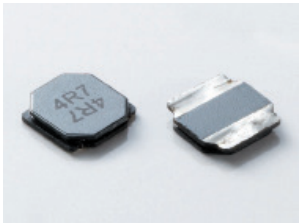
ATNR Series

3010/4010/4018/5010/5012/
6010/6012/6020/8040/5D20/
6D28/7D15



ATNR_M Series

3010/3012/3015/4010/4012/
4018/4030/5010/5040/6010/
6012/6020/6045/8040



ATNR_MH Series

3010/3012/4010/4012/4018/
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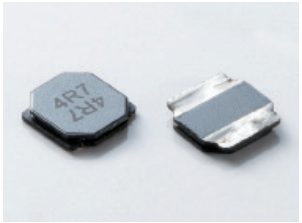


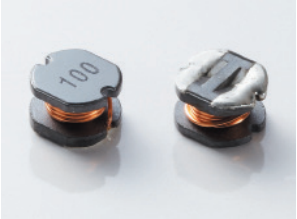
ATNR_MA Series

3010/3015/4012/4018/5020/
5040/6020/6028/6045/8040

SMD Power Inductors

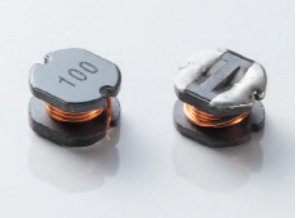
AGPI Series

3D16/4D18/4D28/5012/
5D18/5D28/6012/6D28/
6D38/7D15/7D18/7D25/
7D28/8D43/10D15/10D25



ATPI Series

0302/0403/0504/0703/
0705/1005



ATPI_HF Series

0315/0302/0403/0504/
0703/0705/1006

AFPI Series

1003/1004/1005

ASPI Series

0703/0704/1204/1205/
1207

ASPI_WE Series

0603/0605/0703/0704/
1204/1205/1207/1209

APIW Series

3308/3316/3340/5022

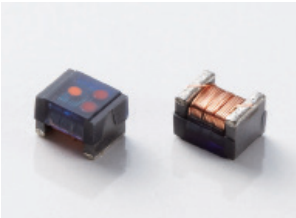
APIR Series

3316/5022

RF Inductors

AOI Series

1005/1608/2012/2520/3225



AOIC Series

1610/2012/2520/3225

AIGC Series

160808/201210/201610/
252010/252012

AIG Series

1608/2012

RF Inductors

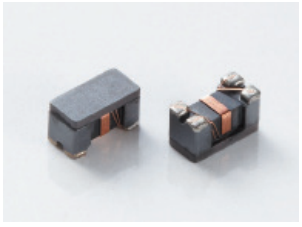
AIF_L Series

1005/1608

ARI Series

B02/B03

EMI Suppression Filters

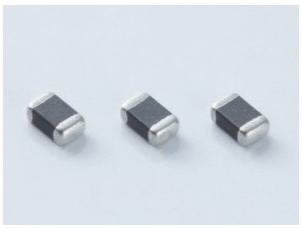


ATCM Series

2012/3216

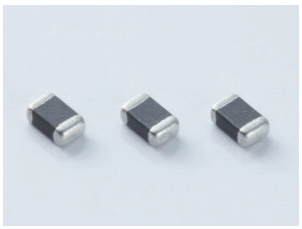
ATCM_HDMI Series

2012



AMB Series

1005/1608/2012

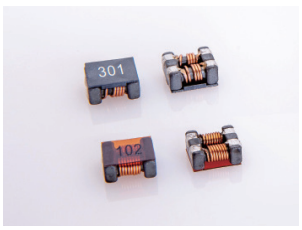


AMC Series

1005/1608/2012

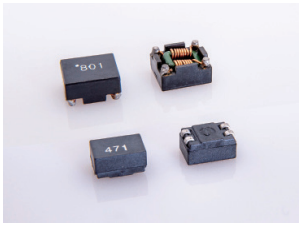
AFIN Series

080630/100850/121060



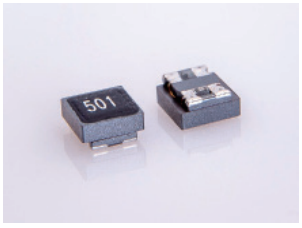
ALCM Series

050520/070640/090750/
090770/121190/131160/
151360



ARCM Series

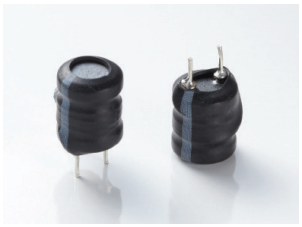
090650/100850



AXCM Series

050530/050550

DIP Power Inductors

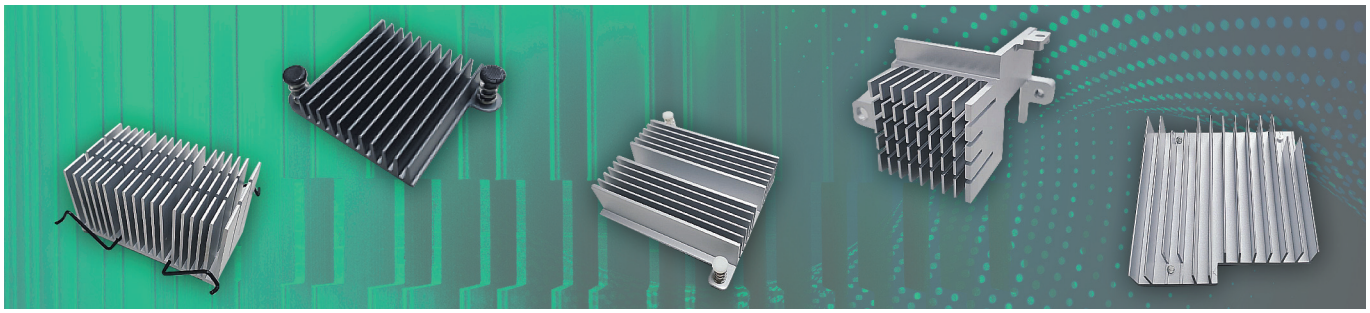


ADR Series

0406/0608/0810/0912

Aluminum Extruded Heat Sink

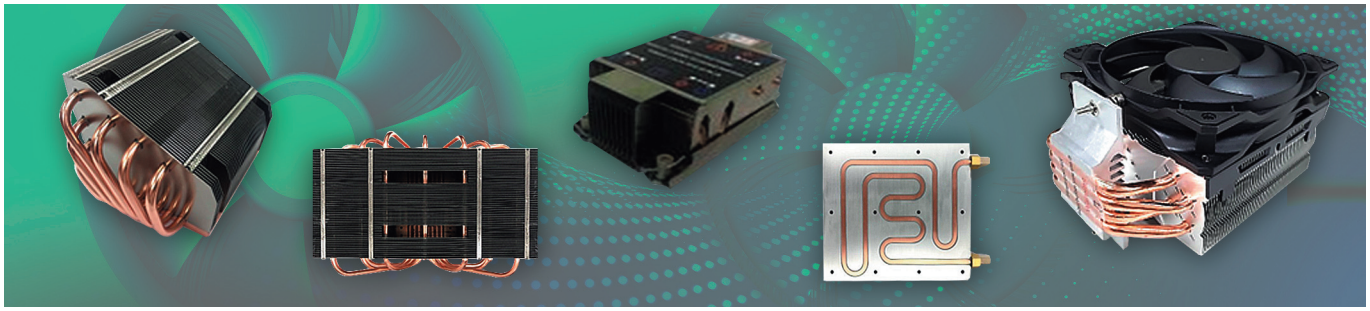
(Note: Can provide customized size and shape according to customer needs)



- Directions: It is currently the most common product design method. It can be made into complex shapes, the mold is relatively low cost and the construction method is mature and stable
- Product Performance: AL6063 material used, thermal conductivity 210 (W/m.K)
- Surface treatment: Blasting / Anodizing / Graphene Coating

Thermal Module Products

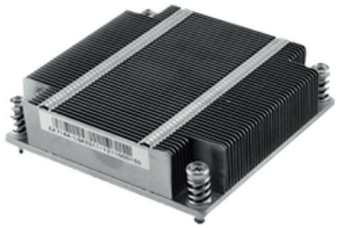
The temperature uniformity of the radiator has a great influence on the heat dissipation performance, and a good temperature uniformity medium is required to achieve it. It is often used in large-size radiators and the common temperature equalization methods are welding VC and Heat Pipe.



Solution for Intel Series

LGA 1150/1151/1156

Program	1U_Passive
TDP(W)	95
Dimension(mm)	L90xW90xH26
material	AL_Base+HeatPipe+ AL_Fin



LGA 1150/1151/1156

Program	1U_Passive
TDP(W)	95
Dimension(mm)	L90xW90xH27
material	AL_Base+HeatPipe+ AL_Fin

LGA 2011

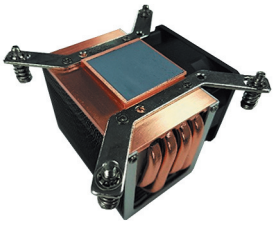
Program	1U_Passive
TDP(W)	95
Dimension(mm)	L104xW80xH27
material	AL_Base+HeatPipe+ AL_Fin

LGA 2011

Program	2U_Active
TDP(W)	95
Dimension(mm)	Ø102.5xH61.5
material	AL_Base+Fan

Fan

Dimension(mm)	Ø92x25
Speed(RPM)	800~3500
Speed Control	PWM
Air Flow(CFM)	59.84
Acoustic Noise(dB)	21~44
Voltage(VDC)	11.4~12.6
Current(A)	0.1~0.38
Bearing	Two Ball
Life(Hour)	70000/40°C
Fan Connector	4pin

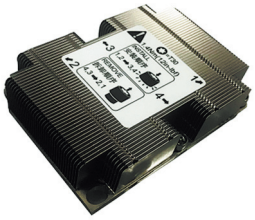


LGA 2011

Program	2U_Active
TDP(W)	130
Dimension(mm)	L93.5xW93.5xH65
material	CU_Base+HeatPipe+ AL_Fin+Fan

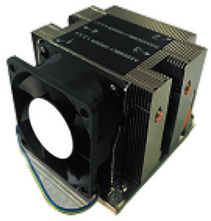
Fan

Dimension(mm)	60x25
Speed(RPM)	2500~6800
Speed Control	PWM
Air Flow(CFM)	39.84
Acoustic Noise(dB)	21~44
Voltage(VDC)	11.4~12.6
Current(A)	0.1~0.38
Bearing	Two Ball
Life(Hour)	70000/40°C
Fan Connector	4pin



LGA 3647_Purley

Program	1U_Passive
TDP(W)	145
Dimension(mm)	L108xW78xH26
material	CU_Base+HeatPipe+ AL_Fin

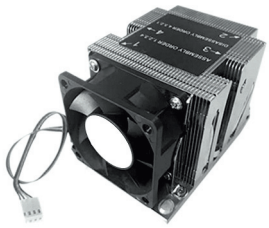


LGA 3647_Purley

Program	2U_Active
TDP(W)	205
Dimension(mm)	L97xW88xH65
material	CU_Base+HeatPipe+ AL_Fin+Fan

Fan

Dimension(mm)	60x25
Speed(RPM)	2500~6800
Speed Control	PWM
Air Flow(CFM)	34.12
Acoustic Noise(dB)	21~44
Voltage(VDC)	11.4~12.6
Current(A)	0.1~0.5
Bearing	Two Ball
Life(Hour)	70000/40°C
Fan Connector	4pin



LGA 3647_Purley

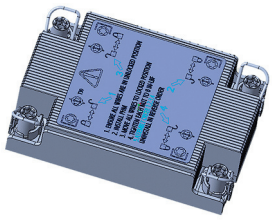
Program	2U_Active
TDP(W)	205
Dimension(mm)	L118xW78xH65
material	CU_Base+HeatPipe+ AL_Fin+Fan

Fan

Dimension(mm)	60x25
Speed(RPM)	2500~6800
Speed Control	PWM
Air Flow(CFM)	34.12
Acoustic Noise(dB)	21~44
Voltage(VDC)	11.4~12.6
Current(A)	0.1~0.5
Bearing	Two Ball
Life(Hour)	70000/40°C
Fan Connector	4pin

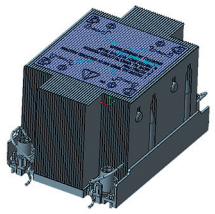
LGA 3647_Purley

Program	2U_Passive
TDP(W)	205
Dimension(mm)	L108xW78xH64
material	CU_Base+HeatPipe+ AL_Fin



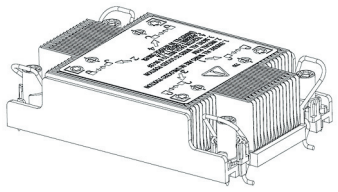
LGA 4189_Whitley

Program	1U_Passive
TDP(W)	165
Dimension(mm)	L113xW78xH25
material	CU_Base+HeatPipe+ AL_Fin



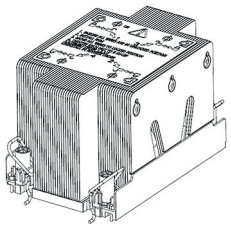
LGA 4189_Whitley

Program	2U_Passive
TDP(W)	205
Dimension(mm)	L113xW79xH64
material	CU_Base+HeatPipe+ AL_Fin



LGA 4677_Eagle Stream

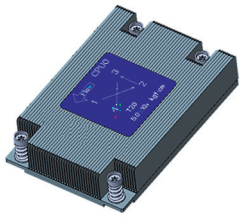
Program	1U_Passive
TDP(W)	300
Dimension(mm)	L118xW78xH24.8
material	CU_Base+HeatPipe+ AL_Fin



LGA 4677_Eagle Stream

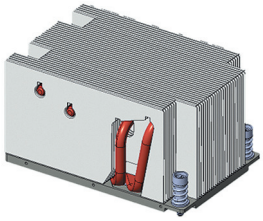
Program	2U_Passive
TDP(W)	350
Dimension(mm)	L118xW78xH64
material	CU_Base+HeatPipe+ AL_Fin

Solution for AMD Series



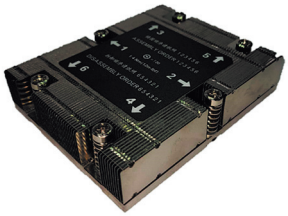
Socket SP3

Program	1U_Passive
TDP(W)	205
Dimension(mm)	L120xW82xH24
material	CU_Base+HeatPipe+ AL_Fin



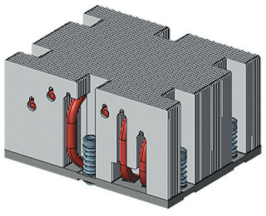
Socket SP3

Program	2U_Passive
TDP(W)	250
Dimension(mm)	L119.3xW78.4xH64
material	CU_Base+HeatPipe+ AL_Fin



Socket SP5

Program	1U_Passive
TDP(W)	400
Dimension(mm)	L118xW92.4xH25
material	CU_Base+HeatPipe+ AL_Fin



Socket SP5

Program	2U_Passive
TDP(W)	400
Dimension(mm)	L118xW92.4xH63
material	CU_Base+HeatPipe+ AL_Fin

High Thermal Conductivity Die-Casting Product

- Directions: Compared with the general ADC12 material, the new material has higher thermal conductivity
- Material : Electrophoresis / graphene Coating
- Surface treatment: Electrophoresis / Graphene Coating

New Material

Density (g/cm³)	2.7
Thermal Conductivity (W/m·K)	176
Tensile Strength (Mpa)	280-305
Yield Strength (Mpa)	115-130
Elongation (%)	4.5-8

ADC12

Density (g/cm³)	2.7
Thermal Conductivity (W/m·K)	176
Tensile Strength (Mpa)	320-360
Yield Strength (Mpa)	140-155
Elongation (%)	4-7

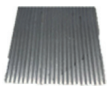
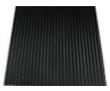
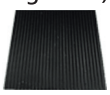
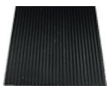
Graphene Spray Product Introduction

Thinner and Shorter
The same heat dissipation performance, adding nano-carbon radiator Height and weight can be reduced by more than 60%

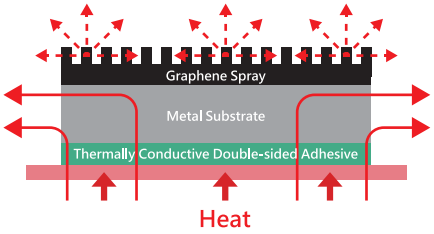
Better Heat Dissipation
When the traditional radiator has the same volume, nano-carbon coating The strong radiation heat dissipation capacity of the layer improves the Cooling efficiency

More Cost-effective
The same heat dissipation performance, adding Graphene Spray can be more cost-effective

Greener and More Environmentally Friendly
Products are environmentally friendly and take a sustainable development route

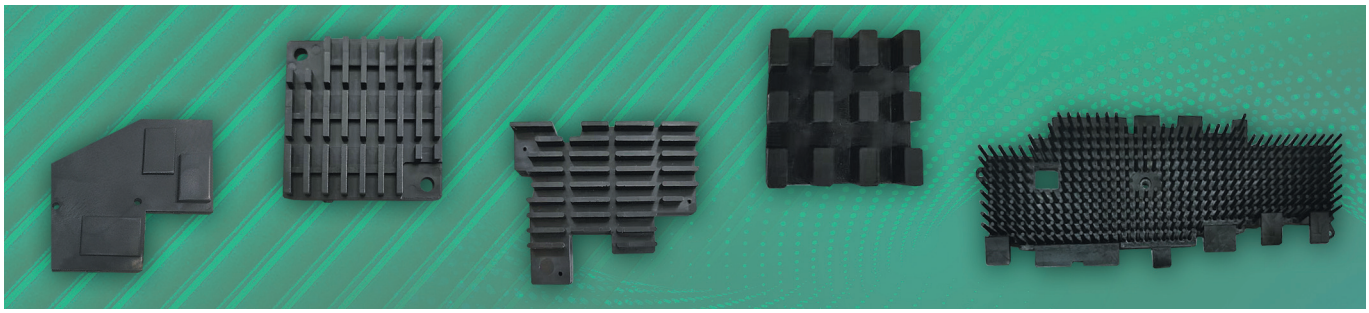
Heat radiation performance comparison	Aluminum extrusion	Anodized black	Graphene Spray (single side)	Graphene Spray (both side)
				
Size(mm)	60×60×2.3	60×60×2.3	60×60×2.3	60×60×2.3
Heater	10×10 5W	10×10 5W	10× 10 5W	10×10 5W
Steady State Temperature Rise (℃)	65.7	56.3	55.9	52

Heat energy is converted to infrared, & take the heat in the form of radiation



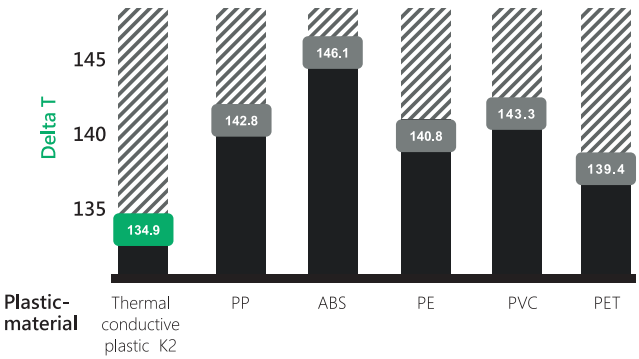
Thermal Conductive Plastic

(Note: Can provide customized size and shape according to customer needs)



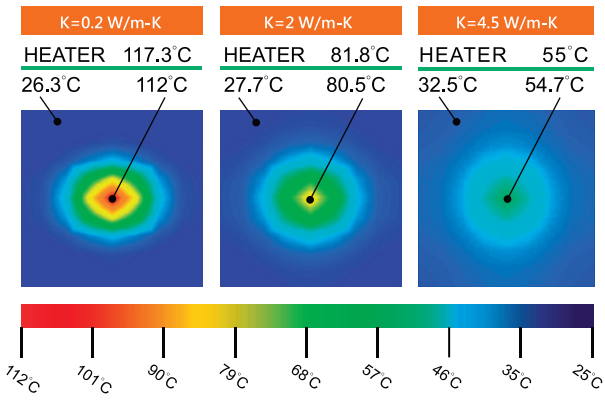
Directions: By adding high thermal conductivity materials, it can be modulated to have higher thermal conductivity coefficient than ordinary plastic parts, and it can have design flexibility equivalent to ordinary plastics.

Thermal Conductive Plastic VS Normal Plastic Thermal Performance Comparison



Size 100*100mm Thickness 3mm Medium Gap Pad K 1.5 t0.5mm)
Heating Wattage 6W

Comparison of the effect of thermal conductive plastic on the improvement of thermal conductivity



Ambiance Temperature 25℃ Medium Gap Pad K 1.5 t0.5mm)
Heating Wattage 5W

Measured temperature

Thermal conductive plastic will not cause EMI interference and has a high heat dissipation effect close to metal through the combination of graphene composites.

01 Delta T 143.3℃
PC Type
Size : 100*100*3mm
Amb Ave. : 23.7℃
6W

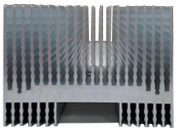
02 Delta T 134.9℃
Thermally Conductive Plastic(K=2)
Size : 100*100*3mm
Amb Ave. : 23.4℃
6W

03 Delta T 58.1℃
Thermally Conductive Plastic(K=2) + Graphene Paper Composite
Size : 100*100*3mm
Amb Ave. : 23.6℃
6W

04 Delta T 56℃
AL1050 Type
Size : 100*100*3mm
Amb Ave. : 23.5℃
6W

Thermal Simulation

In the early stage of development, preliminary scheme design can be carried out through simulation software, which can effectively shorten the development process and reduce development costs.



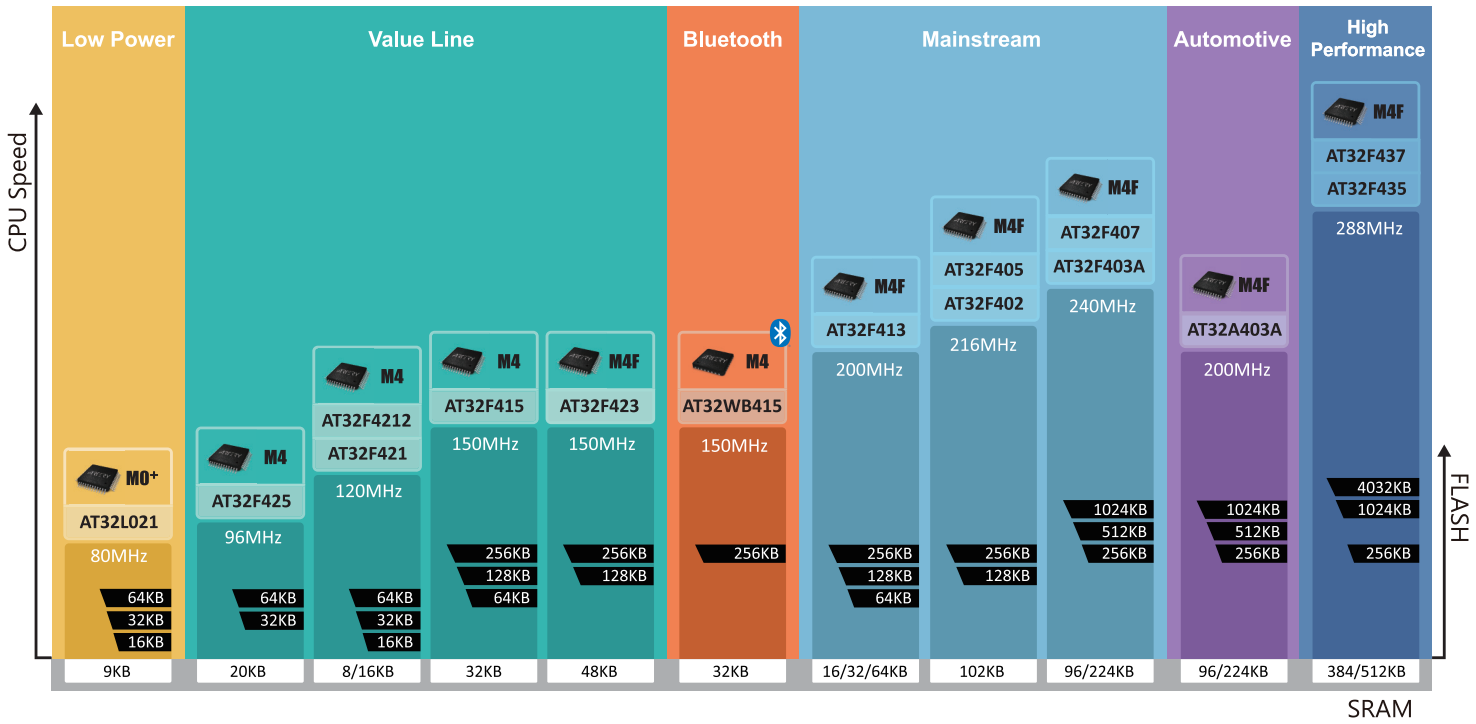
Item	Original clean	Optimized Graphene spray products
Size	70*45*50	70*35*40
Amb Ave.	24℃	23.6℃
Delta T	138.3℃	134℃
Weight	206g	135g
Cost	100%	down 9.3 %

01 Customer provide 3D drawing
02 Customers provide IC thermal resistance and wattage parameters
03 Set thermal simulation parameters
04 Customer's original plan, thermal simulation
05 Analyze the original plan design problem
06 Possible solutions 1~2 cases Perform thermal simulation
07 Analyze whether the degree of comparison and improvement has achieved the goal
08 Goal Achieved / Goal not reached
09 Organize reports and discuss with customers
10 Sample making
11 Samples provide customers with real machine verification
Propose solutions 1~2 again for thermal simulation

Artery Technology Corporation

AT32 MCU

- AEC-Q100 Automotive Qualification
- Bluetooth SIG Bluetooth BQB Certification
- IEC 60730 Appliance Safety Standard
- Industrial-grade Chip Operating Temperature Range



Industry Application (Medical / Communication / New Energy)

- Blood pressure monitor/4G-5G base station/Photovoltaic

Industrial/Motor Control

- Motor/DTU/Electric vehicle controller

Smart Home

- Smart dimmer/Washing machine/Sweeping robot

Consumer/ Commercial Applications

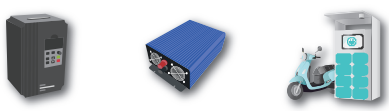
- 3-axis stabilizer/Gaming headset/Robot

Automotive

- OBDII/Car trunk control/ADAS

Power Management

- VFD/Inverter/Charging Station



Artery Technology Corporation

ARM® Cortex®-M4 & M0+

AT32 MCU High Performance, High Stability & Low Power

Low Power

M0+ AT32L021
- Cortex®-M0+Core
- 80MHz CPU
- 64KB Flash, 8+1KB SRAM
- 4xUART, CAN, ADC

Bluetooth

M4 AT32WB415
- Cortex®-M4 Core
- 150MHz CPU
- 256KB Flash, 32KB SRAM
- OTG, CAN, 4xUART, 2xCMP
- BT 5.0 dual mode

Bluetooth

High Performance

M4F AT32F435
- Cortex®-M4F Core
- 288MHz CPU
- 4032KB Flash, 512KB SRAM
- 2xOTG, 2xCAN, 8xUART
- 3x5.33Msps ADC
- 2xQSPI, SDRAM

M4F AT32F437
- Cortex®-M4F Core
- 288MHz CPU
- 4032KB Flash, 512KB SRAM
- 2xOTG, 2xCAN, 8xUART
- 3x5.33Msps ADC, EMAC
- 2xQSPI, SDRAM

Automotive

M4F AT32A403A
- Cortex®-M4F Core
- 200MHz CPU
- 1024KB Flash, 224KB SRAM
- 2xCAN, 8xUART, USB, XMC
- AEC-Q100 Grade 2

Mainstream

M4F AT32F402
- Cortex®-M4F Core
- 216MHz CPU
- 256KB Flash, 96+6KB SRAM
- OTG, QSPI, 8xUART

M4F AT32F405
- Cortex®-M4F Core
- 216MHz CPU
- 256KB Flash, 96+6KB SRAM
- QSPI, 8xUART
- HS+FS OTG with PHY

M4F AT32F413
- Cortex®-M4F Core
- 200MHz CPU
- 256KB Flash, 64KB SRAM
- 2xADC, 2xCAN, USB

M4F AT32F407
- Cortex®-M4F Core
- 240MHz CPU
- 1024KB Flash, 224KB SRAM
- 2xCAN, 8xUART, USB, EMAC

M4F AT32F403A
- Cortex®-M4F Core
- 240MHz CPU
- 1024KB Flash, 224KB SRAM
- 2xCAN, 8xUART, USB, XMC

Value Line

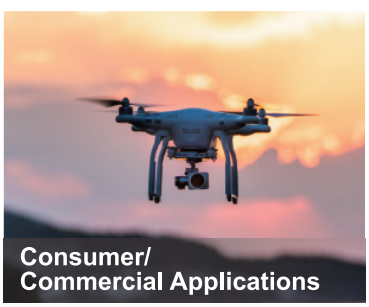
M4 AT32F425
- Cortex®-M4 Core
- 96MHz CPU
- 64KB Flash, 20KB SRAM
- OTG, CAN, 4xUART

M4 AT32F421
- Cortex®-M4 Core
- 120MHz CPU
- 64KB Flash, 16KB SRAM
- CMP, ADC, 2xUART

M4 AT32F4212
- Cortex®-M4 Core
- 120MHz CPU
- 64KB Flash, 16KB SRAM
- CMP, ADC, 2xUART, 2xOPA

M4 AT32F415
- Cortex®-M4 Core
- 150MHz CPU
- 256KB Flash, 32KB SRAM
- OTG, 2xCMP, CAN

M4F AT32F423
- Cortex®-M4F Core
- 150MHz CPU
- 256KB Flash, 48KB SRAM
- OTG, 2xDAC, 2xCAN
- 24ch 5.33Msps ADC



PANJIT SEMI CONDUCTOR

PANJIT International Inc.

Existing Portfolio	Diodes	Transistor	SiC Devices
	Rectifiers Schottky (20-200V) ESD Arrays (≥ 0.2pF) TVS (≤ 6.6KW) Zener (≤ 5W) FRED (600-1200V) Power Bridge	Small Signal MOSFET Power MOSFET General BJT Low Vce(sat) BJT	SiC Diode (650-1200V)

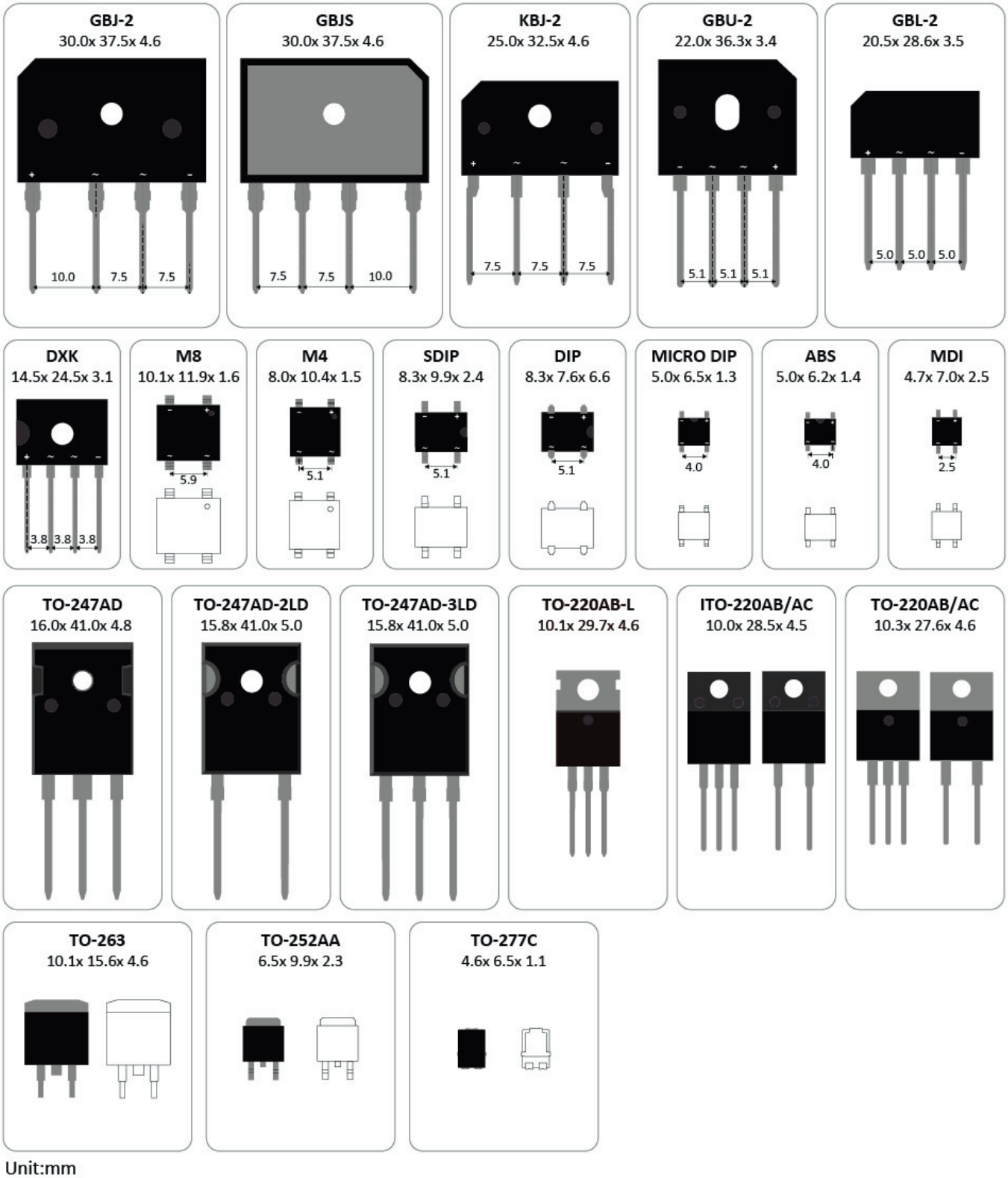
Technology Innovation	Diodes	MOSFET	IGBT	SiC Devices
	FRED (650-1700V) Ultra LVF Power Bridge	SGT MOSFET (40-120V) SJ MOSFET (600-800V)	FS Trench IGBT (650-1700V)	SiC Diode (650V-1700V) SiC MOSFET (650V-1200V)

Surface Mount Type Package Outline

Unit:mm

PANJIT International Inc.

Power Package Outline



Unit:mm

NIDEC Corporation

Medium- and large-size motors

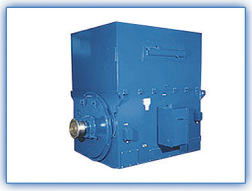

Induction (asynchronous) motors


Synchronous motors


Brushless DC motors


Servo motors


Pump motors


Medium and high voltage motors


Robotics motors

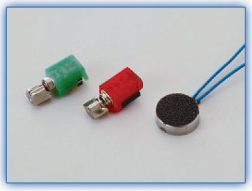
Small-size and precision motors


Brushless DC motors


Geared motors


Coreless motors


Polygon laser scanners


Tactile devices

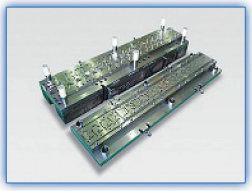

Synchronous motors


Stepping motors


Solenoid


Fans & Blowers

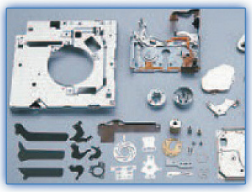
Mold, molding, cutting, and machining components


Mold unit design & production


Gears

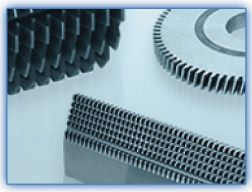

Precision molding components


Cutting components


Press-machined product


Mold


Prototype / Tool


Precision Cutting Tools

NIDEC Corporation

Charger

Nidec offers a wide range of different products in its EV Charging portfolio in order to realize solutions perfectly tailored to the charging scenario for the customer. Our Direct Power DC Fast Charging solution is ready for current and upcoming EV's, which can be charged in less than 15 minutes with a charging power up to 360kW. The 2x22kW Direct Power AC is a charging station that can be connected to the grid and also to any EV management system due to its wide range of communication protocols.The different AC Wallbox versions can additionally be combined for fleet management or home applications. Altogether it could be combined with an operating and/or load management software running on Nidec SCI (Smart Charging Interface)


SCI
(Smart Charging Interface)


Direct Power DC


Direct Power AC


Wallbox

Air Purifier / Electric Fan

Washers/Dryers

Full support to customers including expertise in motors and electronic drives and a worldwide network to serve every country. Nidec provides a full range of motors, specially designed for dishwashers, washing machines, and dryers, which achieve the most advanced efficiency classes, standards, and new regulations. With an extreme energy efficiency level, Nidec motors have a smaller size, lower noise and vibration, and less environmental impact. Designed ahead of European regulations on energy labeling, the motors stand out for their robust design.

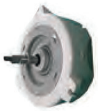
BLDC Motors


Type A


Type C PRO


25H Type


Dryer Motors (BLDC, BPM)


Washer Dryer Motor (BLDC)


Direct Drive Motors for Washing Machines (BLDC)


Actuator Units for Full Automatic Washing Machines


Belt Drive Motors for Washing Machines (BLDC/AC)


Drain Pump Unit

Dishwashers

Nidec motorpumps for dishwashers are the result of deep knowledge and optimization in both electro-mechanic and hydraulic components.
Outstanding results in vibration and noise performance are obtained thanks to optimization of magnetic configuration, allowing Nidec customers to achieve silent operation and low consumptions. Integration of heater is an available option.


Dishwasher Pumps (AC)


Dishwasher Pumps (BLDC, BPM)

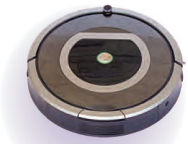

Dishwasher Pump with Integrated Heater

Vacuum Cleaners

BLDC motor characteristic such as small, light-weight and high efficiency, completely meets the cleaner needs to be robotic cleaner and cordless cleaner (recent stick type cleaner), and it makes the cleaner performance much better.

For Robot Cleaner


Motors for Wheel & Main Brush / Robot Blower (BL-V20)



For High-Power Vacuum Cleaner


Blower(V45) Handy Cleaner / Blower(V55) Stick Cleaner / Cleaner Blower(V65) Power Stick

NIDEC Corporation

Tactile Devices

WONDER SENSE is a generic brand name of Nidec tactile technology.

Our Tactile devices creates realistic sense of touch on devices such as smartphones, smart watches and PC with its excellent vibration characteristics. We provide wide variations of devices for design flexibility of our customers.


PC/Tablet


Touch Pad


Smart Phone


HMI


Smart Watch


VR/Game


Robot


Automotive

Physical Surfaces

Physical Bump

Physical Hole

Virtual Surfaces

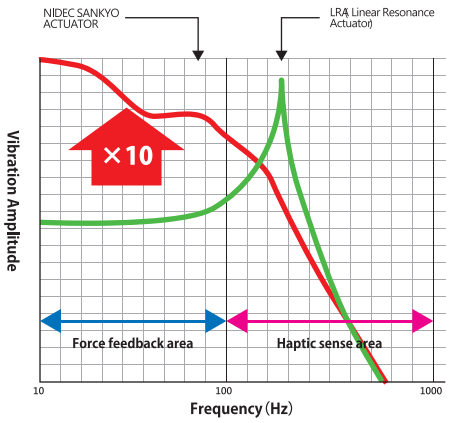
Virtual Bump

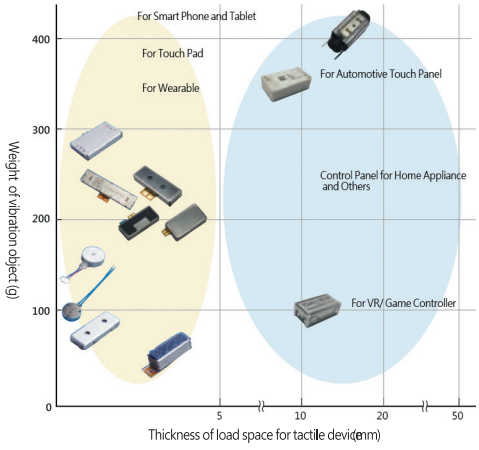
Virtual Hole

A wide range of product line up

Nidec group can provide tactile for a wide range of devices used such as;

- Wearable, Smart phone and tablets, which requires "delicate sense"
- Touch panel for automotive
- VR/Game and others which require large feedback.





Name of Product	Smart Phone / Wearable															Game / Panel		
	Sprinter A	Sprinter D	Sprinter X	Sprinter α	Sprinter β	Sprinter γ	Sprinter Z0825A	Sprinter Z	Sprinter Z1040	HPD	TDA112C07	J0000K21	CA3	CA7-VH5	CA7-VH9	TDA113C08	TDA111C12	SPEAR
Size	2.5t × 6.0w 25.0L	3.0t × 7.0w 20.0L	2.6t × 6.0w 16.0L	3.0t × 11.3w 20.0L	3.1t ×7.4w 16.8L	3.8t × 8.0w 15.0L	φ 8.0 × H2.5	3.5t × 4.0w 12.0L	φ 10 × 4t	φ 8.0 × H2.5	6.4t × 14.6w 24.8L	2.0t × 8.0w 15.0L	φ3.0 × H10.7	φ6.55 × H5.0	φ6.55 × H8.8	10.3t × 16.1w 30.4L	12.8t × 23w 42L	15t × 15.0w 35L
Frequency(F0)	150Hz	180Hz	190Hz	175Hz	200Hz	150Hz	240Hz	230Hz	170Hz	235Hz	1Hz~1KHz (No resonance)	190Hz	190Hz170Hz		150Hz	1Hz~1KHz (No resonance)	120Hz	150Hz
Amount of Vibration (100g)	2.4Grms	2.4Grms	1.6Grms	5.0Grms	2.5Grms	2.5Grms	1.0Grms	1.4Grms	2.2Grms	1.2Grms	0.27Grms (100Hz)	2.5Grms	0.125Grms	0.35Grms	0.625Grms	0.9Grms (120Hz)	4Grms	10Grms

JDX Technology Co.,Ltd.

Chip Electrolytic Capacitors

Dissipation Factor at 120Hz, 20°C (tan δ max)

JDRVT Series

W.V.	6.3	10	16	25	35	50	63	010
(tan δ max)	0.3	0.24	0.2	0.18	0.16	0.14	0.12	.12

JDRVH Series

W.V.	10	16	25	35	50
(tan δ max)	0.24	0.2	0.18	0.16	0.14

JDRVN Series

W.V.	6.3	10	16	25	35	50
(tan δ max)	0.35	0.26	0.24	0.2	0.18	0.18

JDRVK Series

W.V.	6.3	10	16	25	35	50
(tan δ max)	0.3	0.24	0.2	0.18	0.16	0.14

JDRYK Series

W.V.	200	250	400	450
(tan δ max)	0.15	0.15	0.15	0.15

Miniature Aluminum Electrolytic Capacitors

For Switching Power Supply

JDYK Series

105℃ 3000Hrs

JDFM Series

105℃ 4000~6000 Hrs For Switching Power Supply and LED Drive

JDPZ Series

105℃ 2000 ~3000Hrs High Voltage Smaller-sized High Ripple Cuttent

JDPB Series

105℃ 5000~8000Hrs High Voltage Smaller-sized High Ripple Cuttent Long Life

JDSXW Series

105℃ Voltage Venting Specification

JDAX Series

Uitra Mini at urzed for AC-adapter of portabe device

Special Type

JDFHX Series

For Photo f lash

JDAF-NP Series

Nom-Polarized, For Audio Equipment

JDX Technology Co.,Ltd.

Miniature Aluminum Electrolytic Capacitors

Low Impedance

JDFA Series
105℃ 3000Hrs
Low Impedance

JDFLK Series
Ultra High Ripple Current
Low Impedance

JDFK Series
105℃8000~10000Hrs
Low Impedance,High Reliability

JDFL Series
105℃ 2000Hrs
Extremely Low Impedance

JDFD Series
105℃ 4000~6000Hrs
Extremely Low Impedance, High Reliability

JDFT Series
125℃ 1000~4000Hrs
Low Impedance

Standard Type

JDMP Series
85℃ 2000Hrs
General , Standard

JDHM Series
105℃ 2000Hrs
General , Standard

Long Life

JDHT Series
105℃ 5000Hrs
High Reliability

JDLLE Series
105℃ 10000~15000Hrs
High voltage, High Reliability

JDHA Series
125℃ 5000Hrs
High Reliability

JDBT Series
125℃ 4000Hrs
For Automotive

JDRB Series
105℃ 8000~10000Hrs
High voltage, Low Impedance, High Reliability

JDLEX Series
125℃ 3000~5000H rs
High voltage, High Reliability

JDHW Series
130℃ 2000Hrs
High Reliability

Screw Terminal Type

JDSTC Series
Screw Terminal Type

JDLTC Series
105℃ Screw Terminal Type, Long Life

JDHTC Series
105℃ Screw Terminal Type

JDX Technology Co.,Ltd.

Large Size Aluminum Electrolytic Capacitors

Snap-in Type

JDSC Series
Snap-in Teminal Type
85℃ Standard

JDHL Series
Snap-in Teminal Type
105℃ Long Life

JDAP Series
Snap-in Terminal Type with
Standing Overvoltage

JDHK Series
Snap-in Terminal Type High CV

JDHS Series
Snap-in Teminal Type
105℃ Standard

JDYFX Series
Snap-in Terminal Type 20mm High
Wide Tempe-rature Range

JDDQ Series
Snap-in Terminal Type Exhaust type

For Audio Equipment

JDAUDIO Series
Lug / Snap-in Teminal Type
For Audio Equipment

Lug Type Electrolytic Capacitors

JDUD Series
Lug Terminal Type 85℃ Standard

For Inverter And Conditioner

JDGK Series
Fuston /Printed Board Terminal
Type For Inverter And Air- Conditioner

For Photo Flash Applications With Lug Terminal

JDFHK Series
Electrolytic capacitors for photo flash
applications with lug terminal

For Rapid Strobe Flash Applications

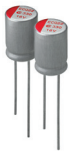
JDFCD Series
Electrolytic capacitors for rapid strobe
flash applications

JDX Technology Co.,Ltd.

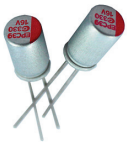
Conductive Polymer Aluminum Solid Capacitors

Radial Type

JDAREA Series
105°C 2000H
2.5~16V
Standard



JDAREC Series
105°C 2000H
2.5~16V
High Current



JDAREP Series
105°C 3000H
6.3~35V
Power

JDAR5K Series
105°C 5000H
2.5~16V
Long Life

JDARHA Series
105 °C 5000H
25V~100V
High Voltage

JDAR5P Series
105°C 5000H
6.3~35V
Power

JDARHE Series
125°C 1000H
2.5~63V
High Endurance

JDARHT Series
125°C 2000H
25V~63V
High Reliability

JDARUP Series
125°C 2000H
2.5~63V
Power

SMD Type

JDAVEA Series
105°C 2000H
2.5~25V
Standard

JDAV5K Series
105°C 5000H
2.5~25V
Long Life

JDAVHA Series
105°C 5000H
2.5~100V
High Voltage

JDAVQC Series
125°C 4000H
25~80V
Standard

Conductive Polymer Hybrid Aluminum Electrolytic Capacitors

SMD Type

JDAVMA Series
105°C 10000H
25~80V

JDAVMC Series
125°C 4000H
25~80V

JDX Technology Co.,Ltd.

Conductive Polymer Aluminum Electrolytic Capacitors

CAP

JDACAS Series
105℃ 2000H
2~25V
Standard

JDACAH Series
105℃ 2000H
2~25V
High Capacitance

JDACTH Series
125℃ 1000H
2~25V
High Reliability

JDACAL Series
105℃ 2000H
2~2.5V

High Capacitance Polymer Aluminum Capacitors (SMLC)

Low ESR & High Ripple

JDSMA Series
105℃ 2000H
3.5x2.8x1.9mm
7.3x4.3x1.9mm

JDSMT Series
125℃ 1000H
3.5x2.8x1.9mm
7.3x4.3x1.9mm

Normal ESR & Ripple

JDSMA Series
105℃ 2000H
3.5x2.8x1.9mm
7.3x4.3x1.9mm

JDSMT Series
125℃ 1000H
3.5x2.8x1.9mm
7.3x4.3x1.9mm

ROHM Co., Ltd

ICs

- Memory
- Amplifiers & Linear
- Clocks & Timers
- Data Converter
- Power Management
- Motor/Actuator Drivers
- LED Drivers
- Display Drivers
- Sensors & MEMS
- Communication LSI
- Speech Synthesis LSI
- Microcontorller
- IC Packages

Power Devices

- SiC Schottky Barrier Diodes
- SiC MOSFETs
- Full SiC Power Modules
- IGBT
- Intelligent Power Modules

Duscrete Devices

- Transistors
- Diodes

Passive Devices

- Conductive Polymer Capacitors
- Tantalum Capacitors

Opto Devices

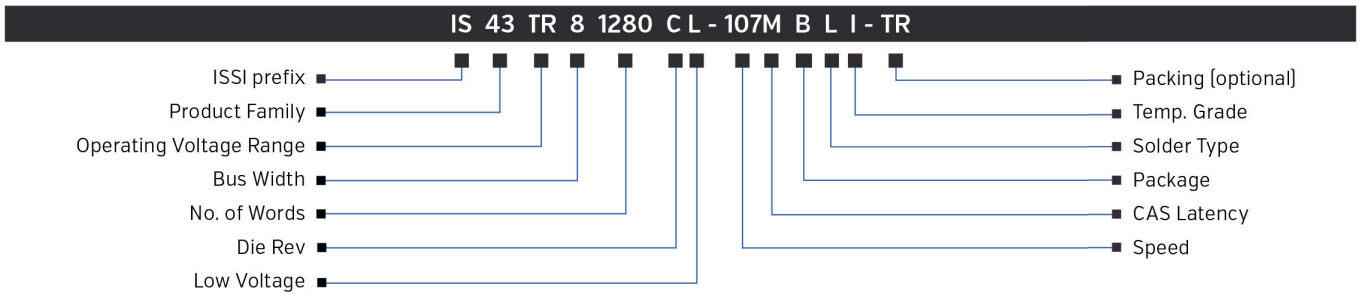
- Laser Diodes
- Optical Sensors

Modeules

- Wireless Modules
- Thermal Printheads

INTEGRATED Silicon Solution, INC.

DRAM Part Decoder



SDRAM Product Family

41 = Asynchronous
42 = SDR Commercial/ Industrial grade
43 = (LP)DDR/DDR2/DDR3/DDR4 Commercial/Industrial grade
45 = SDR Automotive grade
46 = (LP)DDR/DDR2/DDR3/DDR4 Automotive grade

Operating Voltage Range

Asynchronous: Fast Page & EDO
LV = 3.3V

Synchronous:
High Speed
S = 3.3V SDR
VS = 1.8V SDR
R = 2.5V DDR or 2.5V SDR
DR = DDR2
TR = DDR3
QR = DDR4

Low Power

SM/RM/VM = 3.3V/2.5V/1.8V mobile SDR
LR = 1.8V mobile DDR (LPDDR)
LD = LPDDR2
LQ = LPDDR4

Bus Width

8 = x8
16 = x16
32 = x32

No. of Words

100 = 1M
200 = 2M
...
128 = 128M
256 = 256M
512 = 512M
K01 or 1024 = 1G

Monolithic/Stacked, Ranks

(Blank) = Monolithic, Single Rank, unless stated otherwise.
S1 = Stacked, Single Rank
S2 = Stacked, Dual Rank

Generation ("Die Rev")

A-Z (1 characters)
EA-EZ (2 characters) ECC Feature

Low Voltage

DDR3
L = Supports 1.35V & 1.5V

LPDDR4
L = Supports only 0.6V
I/O (LPDDR4X)

Speed

-7 = up to 143Mhz
-6 = up to 166Mhz
-75E = up to 133Mhz @ CL2 (SDR)
-5 = up to 200Mhz
-37 = up to 266Mhz
-3 = up to 333Mhz
-25 = up to 400Mhz
-187 or -18 = up to 533Mhz (1066 Data Rate)
-15 = up to 667 Mhz (1333 Data Rate)
-125 = up to 800Mhz (1600 Data Rate)
-107 = up to 933Mhz (1866 Data Rate)
-093 = up to 1066Mhz (2133 Data Rate)
-083 = up to 1200Mhz (2400 Data Rate)
-075 = Up to 1333Mhz (2666 Data Rate)
-068 = Up to 1466Mhz (2933 Data Rate)
-062 = Up to 1600Mhz (3200 Data Rate)

CAS Latency

B = 3, C = 4, D = 5, E = 6,
F = 7, G = 8, H = 9, J = 10,
K = 11, L = 12, M = 13, N = 14,
P = 15, R = 16, T = 17, U = 18
V = 19, Y = 21, AA = 22
(Blank for some products, whereas only specific speed and CAS Latency combinations exist for others.)

Solder Type

(Blank) = Sn/Pb
L = 100% matte Sn for non-BGA or SnAgCu for BGA

Temp. Grade

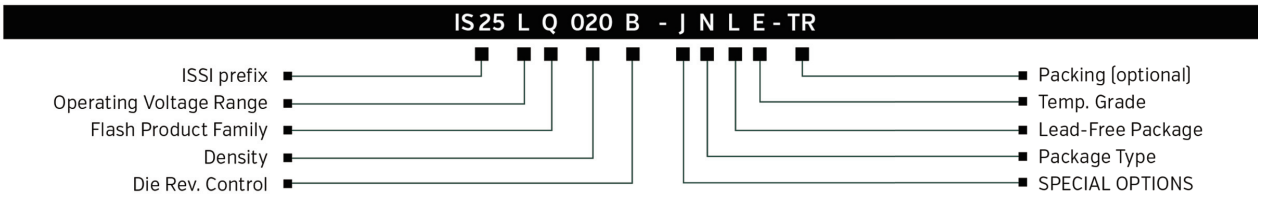
Blank = Commercial Grade (0°C to +70°C)
I = Industrial Grade (-40°C to +85°C)
A1 = Automotive Grade (-40°C to +85°C)
A2 = Automotive Grade (-40°C to +105°C)
A25 = Automotive Grade (-40°C to +115°C
A3 = Automotive Grade (-40°C to +125°C)
(Ambient or case temperature limits shown for most products. Refer to specs.)

Package Type

B = BGA
CT = Copper TSOP
T = TSOP
BP = PoP BGA

INTEGRATED Silicon Solution, INC.

Serial NOR Flash (SPI) Part Decoder



Operating Voltage Range
- L = 2.3-3.6V
- W = 1.65-1.95V

Flash Product Family
- Q = Single/Dual/Quad SPI
- P = Single/Dual/Quad/QPI SPI
  DTR Options Available

Density
- 025 = 256Kb
- 512 = 512Kb
- 010 = 1Mb
- 020 = 2Mb
- 040 = 4Mb
- 080 = 8Mb
- 016 = 16Mb
- 032 = 32Mb
- 064 = 64Mb
- 128 = 128Mb
- 256 = 256Mb
- 512M = 512Mb
- 01G = 1Gb

Die Rev. Control
- Blank = First Rev.

SPECIAL OPTIONS
- J = Standard
- Q = QE bit set to 1
- R = Dedicated RESET#
  in 16-pin SOIC
  or 24-ball BGA

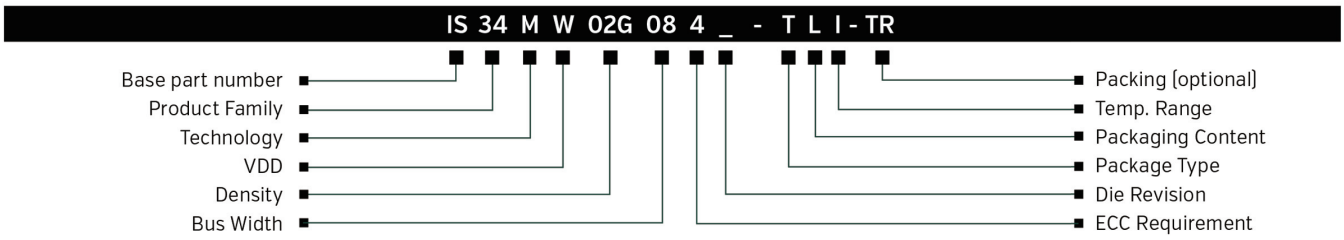
Package Type
- N = 8 pin SOIC 150mil
- B = 8 pin SOIC 208mil
- M = 16 pin SOIC 300mil
- U = 8 pin USON (2x3mm)
- T = 8 pin USON (4x3mm)
- K = 8 pin WSON (6x5 mm)
- L = 8 pin WSON (8x6 mm)
- H = 24 ball (BGA 6x8 mm)
- I = 24 ball (LFBGA 6x8mm)

Lead-free Package
- L = Lead-Free (Pb Free) and Halogen Free

Temperature Grade
- E = Extended grade (-40°C to +105°C)
- A3 = Automotive grade (-40°C to +125°C)

Packing
- TR = Tape and Reel
- Blank = Bulk

SLC NAND Flash Part Decoder



Base part number
- IS = Integrated Silicon
  Solution Inc.

Product Family
- 34 = NAND
- 35 = Automotive NAND

Technology
- M = Standard NAND (SLC)

VDD
- W = 1.8V
- L = 3.3V

Density
- 01G = 1 Gigabit
- 02G = 2 Gigabit
- 04G = 4 Gigabit

Bus Width
- 08 = x8 NAND
- 16 = x16 NAND

ECC Requirement
- 1 = 1-bit ECC
- 4 = 4-bit ECC

Die Revision
- Blank = First Gen.

Package Type
- T = 48-pin TSOP (Type I)[1]
- B = 63-ball VFBGA

Packaging Content
- L = RoHS compliant

Temperature Range
- I = Industrial (-40°C to +85°C)
- E = Industrial (-40°C to +105°C)
- A1 = Automotive Grade (-40°C to +85°C)
- A2 = Automotive Grade (-40°C to +105°C)

Packing (optional)
- Blank = Bulk
- TR = Tape and reel

Note:
1. Call Factory for TSOP1 x16

Puya Semiconductor Co., Ltd.

Nor Flash Package Type

Density	SOP	PDIP	TSSOP	UDFN	MSOP	SOT23	WLCSP	WLCSP	WLCSP
	150mil	8-lead	8-lead	(2x3)	8-lead	5-lead	4 ball	6ball	8ball
2k	●	●	●	●	-	●	-	●	-
4k	●	●	●	●	-	●	-	●	-
8k	●	●	●	●	-	●	-	●	-
16k	●	●	●	●	-	●	-	●	-
32k	●	●	●	●	●	-	●	-	-
64k	●	●	●	●	●	-	●	-	-
128k	●	●	●	●	●	-	●	-	-
256k	●	●	●	●	●	-	●	●	-
512k	●	●	●	●	●	-	●		●
1M	●	●	●	●	●	-	-	-	●

EEPROM Package Type

Density	SOP	SOP	TSSOP	USON	USON	USON	USON	WSON	WLCSP
	150mil	208mil	8-lead	(1.5x1.5)	(2x3)	(3x4)	(4x4)	(6x5)	
512Kb	●								-
1Mb	●		●	●	●				●
2Mb	●		●	●	●			●	-
4Mb	●	●	●	●	●		●	●	●
8Mb	●	●	●	-	●			●	●
16Mb	●	●	●	-	●	●		●	●
32Mb	●	●	●	-	●	●	●	●	●
64Mb	●	●	-	-	-	-	●	●	●
128Mb	-	●	-	-	-	-	-	●	●

Product Types

- Circuit Protective Components
- SolidMatrix® Surface Mount Chip Fuses
- Thin Film SMD Fuse
- AirMatrix® SMD Fuse with 125/250VAC
- Polymer Resettable SMD Fuses
- GcDiode® Ultra-low Capacitance ESD Suppressor
- Multilayer Varistors

Automotive grade SMD products

Technology	Size	Series	Current(A) 0.5 0.75 1 1.5 2 2.5 3 4 5 6 7 8 10 12 15 20
 SolidMatrix@	0603	QF0603H	32Vdc
		QF0603F	63Vdc; 32Vdc; → 24Vdc
	1206	QF1206H	63Vdc; 32Vdc; 24Vdc
		QF1206F	63Vdc; 32Vdc
 AirMatrix@	1206	QA1206F	65Vdc; 32Vdc
	2410	QA2410F	125Vdc; 125Vdc; 65Vdc

Bencent Electronics Co., Ltd.

ESD

DFN0603

3.3x3.3x1.0
420V
6kV@10/700μs

DFN1006

0.6x0.3x0.3
3.3V-12V
42W@8/20μs

SOD523

1.6x0.8x0.6
5~24V
50W~300W@8/20μs

DFN1610

1.6x1.0x0.5
3.3V~15V
100W~1800W@8/20μs

DFN2010

2.0x1.0x0.38
3~5V
75W~200W@8/20μs

DFN2020

2.0x2.0x0.55
4.5~24V
2900W~6000W@8/20μs

DFN2510

2.5x1.0x0.58
3.3-5V
100W@8/20μs

SOT523

1.6x1.6x0.75
5V
60W~100W@8/20μs

SOD323

2.5x1.28x1.0
2.5~36V
150W~500W@8/20μs

SOD123

3.7x1.8x1.0
5~220V
200W~400W@10/1000μs

SOT23-3

2.9x2.4x1.0
3.3~36V
60W~400W@8/20μs

SOT143

2.9x2.4x1.0
5V
125W@8/20μs

SOT23-6

3.0x2.8x1.1
3.3-5V
75W@8/20μs

SOP-8

6.0x4.9x1.55
3.3~58V
450W~2700W@8/20μs

Zener

SOD-323

2.5x1.28x1.0
5.1~20V
200mW ±2%

SOD-323

2.5x1.28x1.0
2.4~39V
200mW ±5%

SOD-323

2.5x1.28x1.0
2.4~43V
200mW ±6%

SOD-123

3.6x1.55x1.2
5.1~20V
350mW ±2%

SOD-123

3.6x1.55x1.2
2.4~39V
350mW ±5%

SOD-123

3.6x1.55x1.2
2.4~43V
350mW ±6%

SOT-23

2.9x2.4x1.1
2.4~43V
300mW ±6%

Bencent®

Bencent Electronics Co., Ltd.

GDT

BS

3.0x1.6x1.6
90~400V
500A@8/20μs

BL

2.9x2.1x1.9
90~400V
500A~1kA@8/20μs

BG

2.9x2.1x1.9
90~600V
150A@10/700μs

BZ

3.2x2.5x2.5
90~800V
1kA@8/20μs

B3A

4.2x2.7x3.9
420V
2kA@8/20μs

BA/BC

4.5x3.2x2.7
75~600V
1kA~3kA@8/20μs

BX

4.2x3.5x3.5
90~400V
3kA@8/20μs

BF

4.2x5.0x5.0
90~1000V
3kA~5kA@8/20μs

BN

5.5x4.0x4.0
70~3600V
3kA~5kA@8/20μs

BJ

5.5x5.0x5.5
90V
5kA~10kA@8/20μs

B3Y

6.8x3.2x2.3
470V
1kA@8/20μs

B3Q

6.8x3.5x3.5
90~420V
2kA~6kA@8/20μs

B3D

7.8x5.0x6.0
75~650V
5kA~10kA@8/20μs

BW

7.0x6.0x6.0
90~3000V
3kA~10kA@8/20μs

BGA

8.0x7.0x2.0
150~800V
500A~1kA@8/20μs

BM

6.0x8.3x8.3
90~800V
10kA~20kA@8/20μs

B5G

Φ5.5x6
70~3600V
3kA~5kA@8/20μs

B8G

Φ8.0x6.0
90~4000V
5kA~20kA@8/20μs

BGO-LB2

Φ5.5x6.0
600V
3kA~5kA@8/20μs

BGO-LC2

Φ8.0x7.0
600~1000V
5kA~10kA@8/20μs

BE-MTW

10.3x8.0x2.3
90~600V
10kA@8/20μs

BE-STW

10.5x8.0x1.6
90~700V
5kA~10kA@8/20μs

BD

16.5x8.3x9.5
1200V
20kA@8/20μs

BU

Φ16x4.6
90~800V
20~120kA@8/20μs

BGO-LF2

Φ21.0x25.0x8.2
1000V
20kA@8/20μs

BMG7D

Φ9.5x13.0x8.0
AC 52~460V
1kA@8/20μs

BMG10D

Φ14.0x17.0x8.6
AC90~400V
2kA@8/20μs

BMG14D

Φ17.5x21.0x8.0
AC90~400V
3kA@8/20μs

BMG20D

Φ22.5x25.0x9.5
AC90~400V
5kA@8/20μs

Bencent Electronics Co., Ltd.

TSS

SOD123

3.6x1.55x1.2
6V
36A@8/20μs

SOT23-5

3.0x2.8x1.25
8~24V
50A@8/20μs

DFN3.3

3.3x3.3x1.0
420V
6kV@10/700μs

SMA

5.25x2.85x2.5
6~400V
4kV@10/700μs

SMB

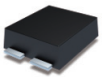
5.45x3.75x2.6
6V~400V
6kV@10/700μs

SMB-F

5.4x3.3x2.0
6V~750V
6kV@10/700μs

SMB-T

5.4x3.3x2.0
6V~400V
6kV@10/700μs

SMC-T

8.0x5.9x2.0
6V
3kA@8/20μs

TVS

BVF-D5

1.6x0.8x0.6
5V
12A@8/20μs

SMA

5.25x2.85x2.5
5V~110V
400W

SMB

5.45x3.75x2.6
5V~110V
600W

SMB-T

5.4x3.3x2.0
15~30
200~1000A@8/20μs

BVF-MD2

5.4x3.3x2.0
15~28V
250A~500A@8/20μs

SMC

8.25x6.15x2.95
5V~110V
1500W

SMC-T

8.0x5.9x2.0
18~75V
3000W

5SMD

8.25x6.15x2.95
5V~110V
5000W

SMD

8.25x6.15x2.95
5V~110V
3000W

SMK

10.5x8.2x2.2
15~400V
1kA-3kA@8/20μs

SME

18.3x14.0x7.5
66~86V
10kA@8/20μs

BVS

18.3x14.0x7.5
66~86V
10kA@8/20μs

DO-218AB

15.5x10.0x4.9
10~43V
6600W

DO204AL(DO41)

Φ2.5x5
6.8~440V
400W

DO204AC(DO15)

Φ3.0x7
6.8~600V
600W

DO201AE

Φ5x9
6.8~440V
1500W

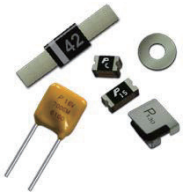
R6/P600

Φ9x9
5~188V
5kW、8kW、15kW

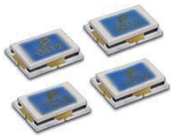
POLYTRONICS Technology Corp.

Over-Current Product

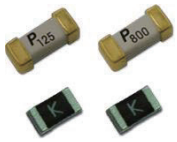
PPTC

Product	Features	Application
	SMD: 0402~2920 series RLD: DC 6V~72V STRAP: DC 6V to 30V , Imax 40A to 100A HVR: 250Vac to 600Vac	Computer Multimedia Mobile phone Battery Portable electronics Game console Industrial controls Telephony and broadband

CLM

Product	Features	Application
	DC 62V max voltage and 12A,15A and 30A Current carrying capacity.	Notebook Cell phone Ultrabook Security systems Tablet PC Automotive applications Printer

FUSE

Product	Features	Application
	DC 35V~50V Interrupting Rating. 1.0A~6.0A Current Rating.	Battery packs Cell phones Chargers DVD players Digital cameras Peripherals LCD monitors and modules Portable device battery PC related equipment Wireless base station Game equipments

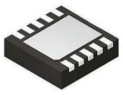
Zhuhai Boya Technology Co., Ltd.

SPI NOR Flash

Item	Specification	Storage Capacity	Packaging
3.3V 32M 150mil	BY25Q32BSTIG(T)	32	SOP8
3.3V 32M 208mil	BY25Q32BSSIG(T)	32	SOP8
3.3V 16M 150mil	BY25Q16BSTIG(T)	16	SOP8
3.3V 16M QPI 208mil	BY25Q16BSSIG(T)	16	SOP8
3.3V 16M 150mil	BY25D16ASTIG(T)	16	SOP8
3.3V 16M 208mil	BY25D16ASSIG(T)	16	SOP8
3.3V 8M 150mil	BY25D80ASTIG(T)	8	SOP8
3.3V 8M 208mil	BY25D80ASSIG(T)	8	SOP8

BY25Q32BS

The BY25Q32BS is 32M-bit Serial Peripheral Interface(SPI) Flash memory, and supports the Dual/Quad SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO), I/O2 (/WP), and I/O3 (/HOLD). The Dual I/O data is transferred with speed of 216Mbits/s


WSON 6 5 mm)

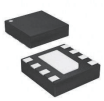

SOP 208 mil

BY25Q16BS

The BY25Q16BS is 16M-bit Serial Peripheral Interface(SPI) Flash memory, and supports the Dual/Quad SPI as well as 2-clocks instruction cycle Quad Peripheral Interface (QPI): Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO), I/O2 (/WP), and I/O3 (/HOLD).

BY25D16

The BY25D16 is 16M-bit Serial Peripheral Interface (SPI) Flash memory, and supports the Dual SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO). The Dual Output data is transferred with speed of 108Mbits/s. The device uses a single low voltage power supply


USON8 3*3 mm


SOP8 208 mil


SOP8 150 mil

BY25D80

The BY25D16 is 16M-bit Serial Peripheral Interface (SPI) Flash memory, and supports the Dual SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO). The Dual Output data is transferred with speed of 108Mbits/s. The device uses a single low voltage power supply


SOP8 208 mil


SOP8 150 mil

Zhuhai Boya Technology Co., Ltd.

SPI NOR Flash

Item	Specification	Storage Capacity	Packaging
3.3V 4M 150mil	BY25D40ASTIG(T)	4	SOP8
3.3V 16M 150mil	BY25Q16BSTIG(T)	16	SOP8
3.3V 16M QPI 208mil	BY25Q16BSSIG(T)	16	SOP8
3.3V 16M 150mil	BY25D16ASTIG(T)	16	SOP8
3.3V 16M 208mil	BY25D16ASSIG(T)	16	SOP8

BY25D40

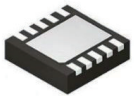
The BY25D40 is 4M-bit Serial Peripheral Interface (SPI) Flash memory, and supports the Dual SPI:Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO). The Dual Output data is transferred withspeed of 108Mbits/s. The device uses a single low voltage power supply, ranging from 2.7 Volt to3.6 Volt.


SOP8 150-mil


SOP8 208-mil

BY25Q64AS

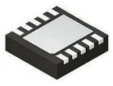
The BY25Q64AS is 64M-bit Serial Peripheral Interface(SPI) Flash memory, and supports the Dual/Quad SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO), I/O2 (/WP), and I/O3 (/HOLD). The Dual I/O data is transferred with speed of 240Mbits/s


WSON (6*5 mm)


SOP 208 mil

BY25Q128AS

The BY25Q128AS is 128M-bit Serial Peripheral Interface(SPI) Flash memory, and supports the Dual/Quad SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO), I/O2 (/WP), and I/O3 (/HOLD). The Dual I/O data is transferred with speed of 240Mbits/s


WSON (5*6 m m)


SOP 208 mil

BY25Q256FS

The BY25Q256FS is 256M-bit Serial Peripheral Interface(SPI) Flash memory, supports the Dual/Quad SPI: Serial Clock, Chip Select, Serial Data I/O0 (SI), I/O1 (SO), I/O2 (/WP), and I/O3 (/HOLD), Reset; and supports the QPI: Serial Clock, Chip Select, I/O0, I/O1, I/O2, and I/O3, Reset

Design Solutions

IOT Oriented Design

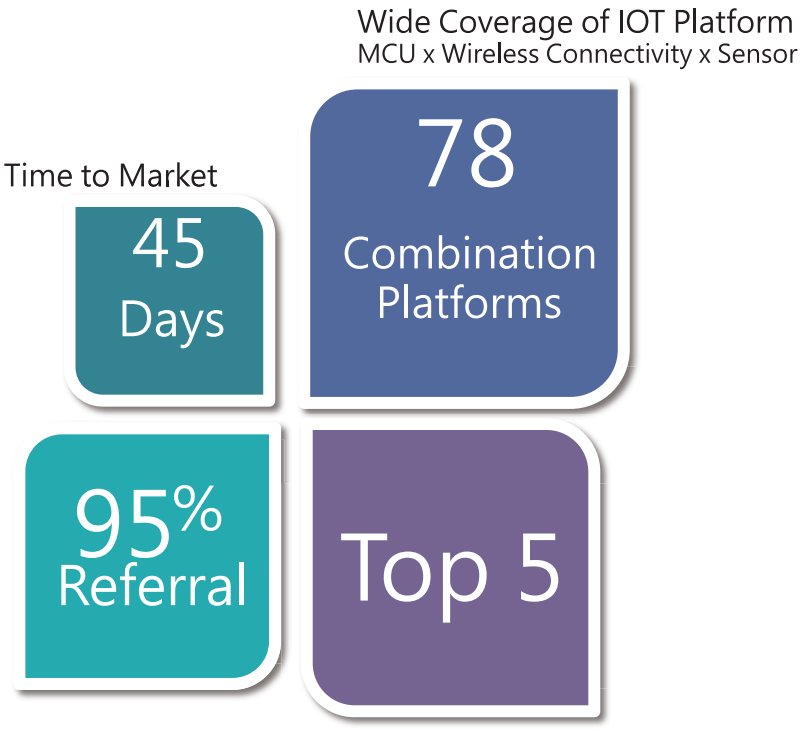
DMF (Deisgn for Manufacturing)
Electronics and Mechanics Integration

Assistant of Product Requirement Check
SPEC Communication and Confirmation

Connectivity
Connection, Sensing, Control-Over Integration

Software
Firmware Programming & User Interface Software Support

Advantages



Design Solutions

IOT Showcase

▶ IOT

Lighting

1. Sleep-Aid Light
2. LED Grow Light
3. Smart Lighting

Industrial

1. Stepping Motor Remote Control
2. BMS (Battery Management System)
3. Production Programming Test

SmartHome

1. Smart Gas Meter
2. Alexa Voice Control
3. Gesture Control Lighting

Entertaining

1. Game Pad
2. Smart Spinning Bike Platform
3. Smart Bat

Health Care

1. Heart Rate Sensing Device
2. TENS
3. Smart Litter Box for Cat

IOT Showcase_by Solution

▶ MCU/Wireless/Sensor

MCU

CortexFamily
Firmware coding

ARTERY
MARVELL
QUALCOMM
MEDIATEK
Texas Instruments
STM32W6
MICROCHIP
REALTEK

Connectivity

Wireless Communication support via Broadband, Near-Field, GPS Technology, LTE.

NB-IoT
GPS
LTE
Wi Fi

Sensor/ Controller

Integration of Sensors, Controllers, Mobile APP, and OS.

3-axis
360°
amazon alexa
iOS